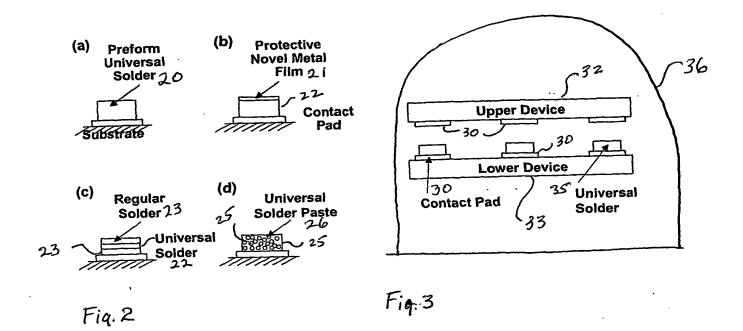
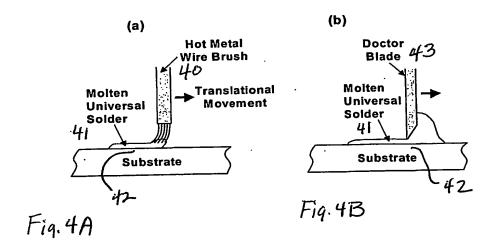
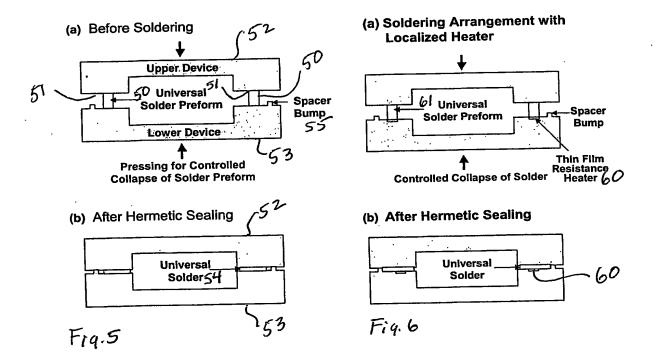
٠-۱		<u> </u>
H	Provide articles having	NA
	bonding surfaces	
. ·	V	
	Dispose universal solder	
1	or braze between	NB
	bonding surfaces	
; "	- V	·
	Wet the surfaces with	
-	solder and bond, under	NC
-	substantially oxygen-free	
٠	conditions.	
L		L

Fiq. 1







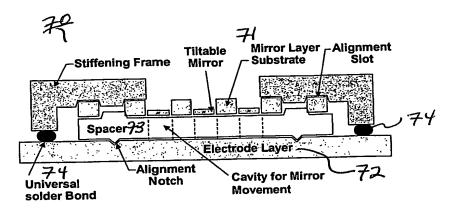


Fig. 7

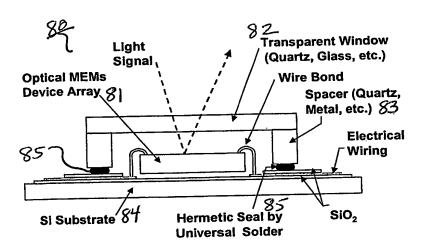
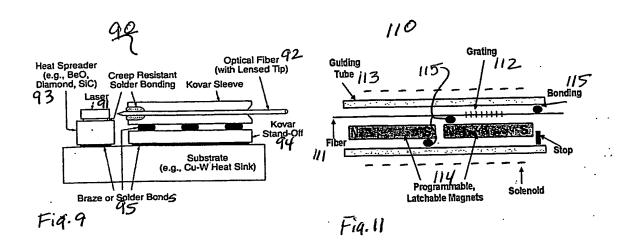


Fig.8



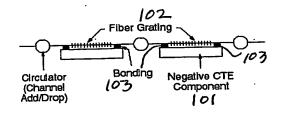


Fig. 10